SNx4ACT74 Dual Positive-Edge-Triggered D-Type Flip-Flops

1 Features

- 4.5V to 5.5V V_{CC} operation
- Inputs accept voltages to 5.5V
- Max t_{pd} of 10.5ns at 5V
- Inputs are TTL-voltage compatible

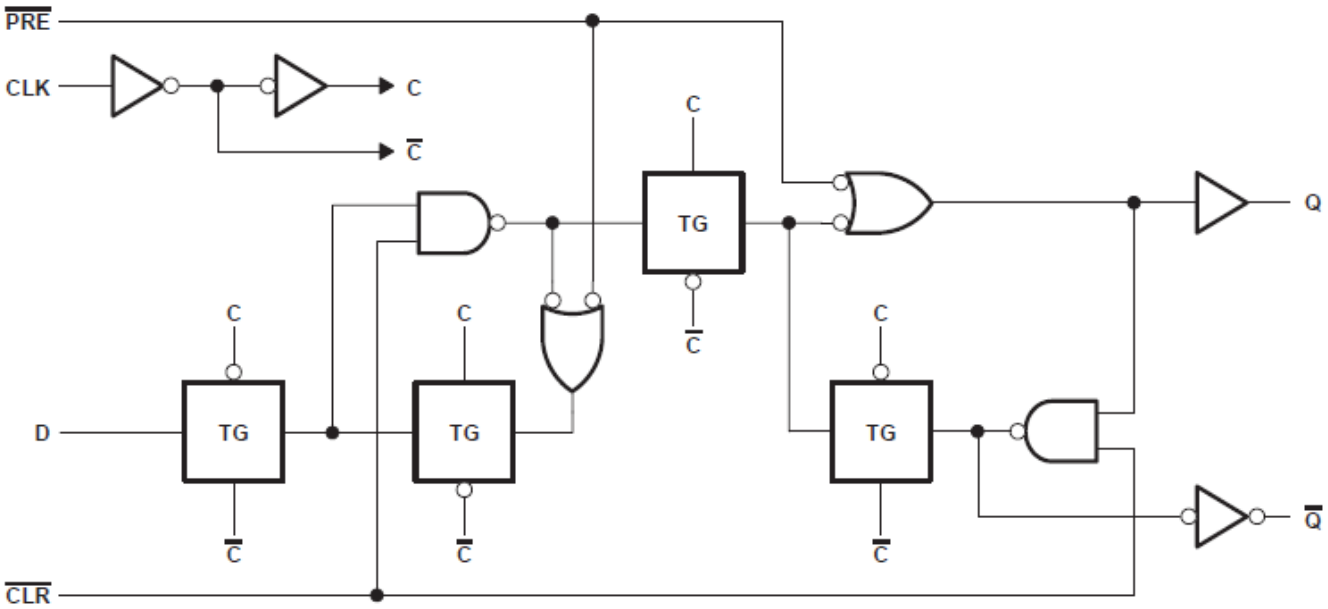
2 Description

The 'ACT74 dual positive-edge-triggered devices are D-type flip-flops.

Device Information

PART NUMBER	PACKAGE(1)	PACKAGE SIZE (2)	BODY SIZE(3)
SNx4ACT74	PW (TSSOP, 14)	5mm × 6.4mm	5mm × 4.40mm
	D (SOIC, 14)	8.65mm × 6mm	8.65mm × 3.9mm
	DB (SSOP, 14)	6.2mm × 7.8mm	6.2mm × 5.3mm
	N (PDIP, 14)	19.3mm × 9.4mm	19.3mm × 6.35mm
	NS (SOP, 14)	10.2mm × 7.8mm	10.3mm × 5.3mm
	BQA (WQFN)	3mm × 2.5mm	3mm × 2.5mm

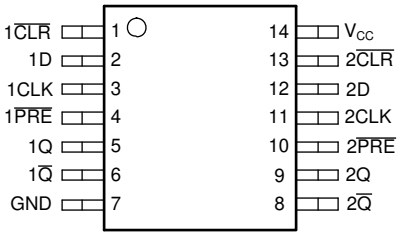
(1) For more information, see Mechanical, Packaging, and Orderable Information.
(2) The package size (length × width) is a nominal value and includes pins, where applicable.
(3) The body size (length × width) is a nominal value and does not include pins.



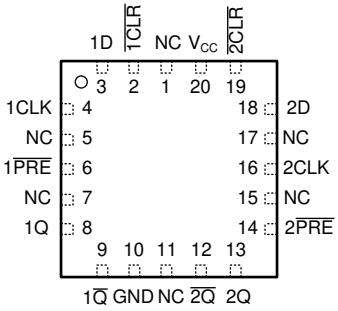
Logic Diagram (Positive Logic)

Table of Contents

3 Pin Configuration and Functions



SN54ACT74 J or W Package; SN74ACT74 D, DB, N, NS, PW (Top View)



SN54ACT74 FK Package (Top View)

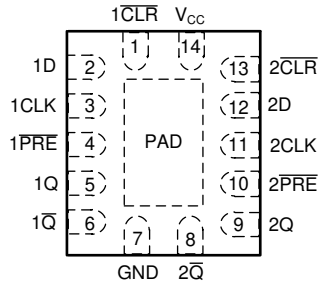


Figure 3-1. SN54ACT74 BQA Package (Top View)

PIN		TYPE[1]	DESCRIPTION
NAME	NO.		
1 $\overline{CLR}$	1	Input	Channel 1, Clear Input, Active Low
1D	2	Input	Channel 1, Data Input
1CLK	3	Input	Channel 1, Positive edge triggered clock input
1 $\overline{PRE}$	4	Input	Channel 1, Preset Input, Active Low
1Q	5	Output	Channel 1, Output
1 $\overline{Q}$	6	Output	Channel 1, Inverted Output
GND	7	—	Ground
2 $\overline{Q}$	8	Output	Channel 2, Inverted Output
2Q	9	Output	Channel 2, Output
2 $\overline{PRE}$	10	Input	Channel 2, Preset Input, Active Low
2CLK	11	Input	Channel 2, Positive edge triggered clock input
2D	12	Input	Channel 2, Data Input
2 $\overline{CLR}$	13	Input	Channel 2, Clear Input, Active Low
V_{CC}	14	—	Positive Supply

(1) Signal Types: I = Input, O = Output, I/O = Input or Output

4 Specifications

4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		–0.5	7	V
V_I	Input voltage(2)		–0.5	V_{CC} + 0.5	V
V_O	Voltage range applied to any output in the high-impedance or power-off state(2)		–0.5	V_{CC} + 0.5	V
I_{IK}	Input clamp current	(V_I < 0 or V_I > V_{CC})		±20	mA
I_{OK}	Output clamp current	(V_O < 0 or V_O > V_{CC})		±20	mA
I_O	Continuous output current	(V_O = 0 to V_{CC})		±50	mA
	Continuous current through V_{CC} or GND			±200	mA
T_{stg}	Storage temperature range		–65	150	°C

4.2 Recommended Operating Conditions

over recommended operating free-air temperature range (unless otherwise noted)

		SN54ACT74		SN74ACT74		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–24	mA
I_{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise and fall rate		8		8	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

4.3 Thermal Information

THERMAL METRIC(1)		SN74ACT74						
		BQA (WQFN)	D (SOIC)	DB (SSOP)	N (PDIP)	NS (SOP)	PW (TSSOP)	UNIT
		14 PINS						
$R_{\theta JA}$	Junction-to-ambient thermal resistance	91.3	119.9	96	80	76	145.7	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	99.4	—	—	—	—	—	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	60.1	—	—	—	—	—	°C/W
ψ_{JT}	Junction-to-top characterization parameter	14.5	—	—	—	—	—	°C/W
ψ_{JB}	Junction-to-board characterization parameter	60.8	—	—	—	—	—	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	37.0	—	—	—	—	—	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC package thermal metrics* application report.

4.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54ACT74		SN74ACT74		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50µA	4.5V	4.4	4.49		4.4		4.4		V
		5.5V	5.4	5.49		5.4		5.4		
	I_{OH} = –24mA	4.5V	3.86			3.7		3.76		
		5.5V	4.86			4.7		4.76		
	I_{OH} = –50mA† (1)	5.5V				3.86				
	I_{OH} = –75mA† (1)	5.5V						3.85		
V_{OL}	I_{OL} = 50µA	4.5V		0.001	0.1		0.1		0.1	V
		5.5V		0.001	0.1		0.1		0.1	
	I_{OL} = 24mA	4.5V			0.36		0.5		0.44	
		5.5V			0.36		0.5		0.44	
	I_{OL} = 50mA† (1)	5.5V					1.65			
	I_{OL} = 75mA† (1)	5.5V							1.65	
I_I	V_I = V_{CC} or GND	5.5V			±0.1		±1		±1	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5V			2		40		20	µA
ΔI_{CC}‡ (2)	One input at 3.4V, Other inputs at GND or V_{CC}	5.5V		0.6			1.6		1.5	mA
C_i	V_I = V_{CC} or GND	5V		3						pF

(1) Not more than one output should be tested at a time, and the duration of the test should not exceed 2ms.
(2) This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0V or V_{CC}.

4.5 Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see Load Circuit and Voltage Waveforms)

			T_A = 25°C		SN54ACT74		SN74ACT74		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency			145		85		125	MHz
t_w	Pulse duration	$\overline{PRE}$ or $\overline{CLR}$ low	5		7		6		ns
		CLK	5		7		6		
t_{su}	Setup time, data before CLK↑	Data	3		4		3.5		ns
			0		0.5		0		
t_h	Hold time, data after CLK↑	$\overline{PRE}$ or $\overline{CLR}$ inactive	1		1		1		ns

4.6 Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Load Circuit and Voltage Waveforms)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ACT74					SN74ACT74					UNIT
			T_A = 25°C			MIN	MAX	T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			MIN	TYP	MAX			
f_{max}			145	210		85		145	210		125		MHz
t_{PLH}	$\overline{PRE}$ or $\overline{CLR}$	Q or $\overline{Q}$	1	5.5	9.5	1	11.5	3	5.5	9.5	2.5	10.5	ns
t_{PHL}			1	6	10	1	12.5	3	6	10	3	11.5	

over recommended operating free-air temperature range (unless otherwise noted) (see Load Circuit and Voltage Waveforms)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ACT74					SN74ACT74					UNIT
			T_A = 25°C			MIN	MAX	T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			MIN	TYP	MAX			
t_{PLH}	CLK	Q or $\overline{Q}$	1	7.5	11	1	14	4	7.5	11	4	13	ns
t_{PHL}			1	6	10	1	12	3.5	6	10	3	11.5	

4.7 Operating Characteristics

V_{CC} = 5V, T_A = 25°C

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50pF,	f = 1MHz	45	pF

5 Parameter Measurement Information

C_L includes probe and jig capacitance. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1MHz, ZO = 50Ω, tr ≤ 2.5ns, tf ≤ 2.5ns. The outputs are measured one at a time with one input transition per measurement.

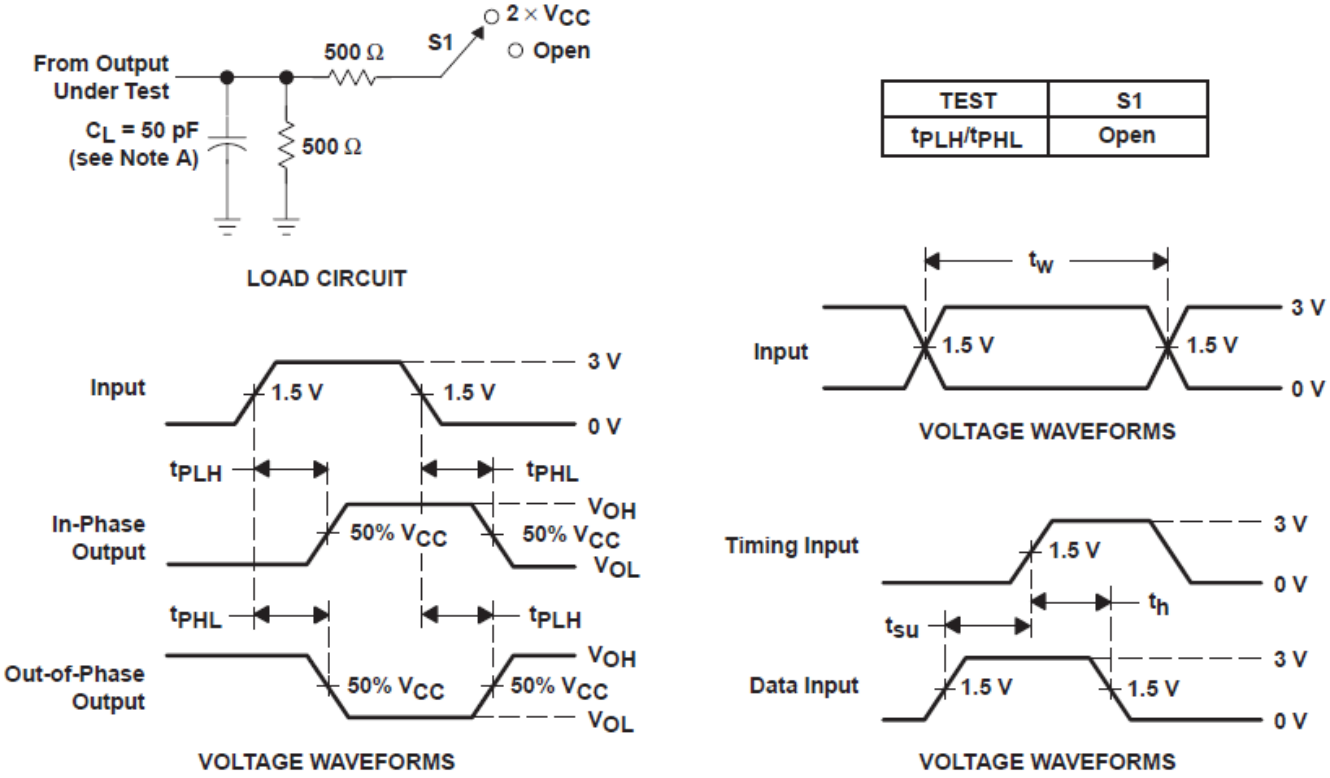


Figure 5-1. Load Circuit and Voltage Waveforms

Note

A. C_L includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1MHz, ZO = 50Ω, tr ≤ 2.5ns, tf ≤ 2.5ns.

C. The outputs are measured one at a time, with one input transition per measurement.

6 Detailed Description

6.1 Overview

A low level at the preset ($\overline{PRE}$) or clear ($\overline{CLR}$) input sets or resets the outputs, regardless of the levels of the other inputs. When $\overline{PRE}$ and $\overline{CLR}$ are inactive (high), data at the data (D) input meeting the setup-time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, changing data at D does not affecting the levels at the outputs.

6.2 Functional Block Diagram

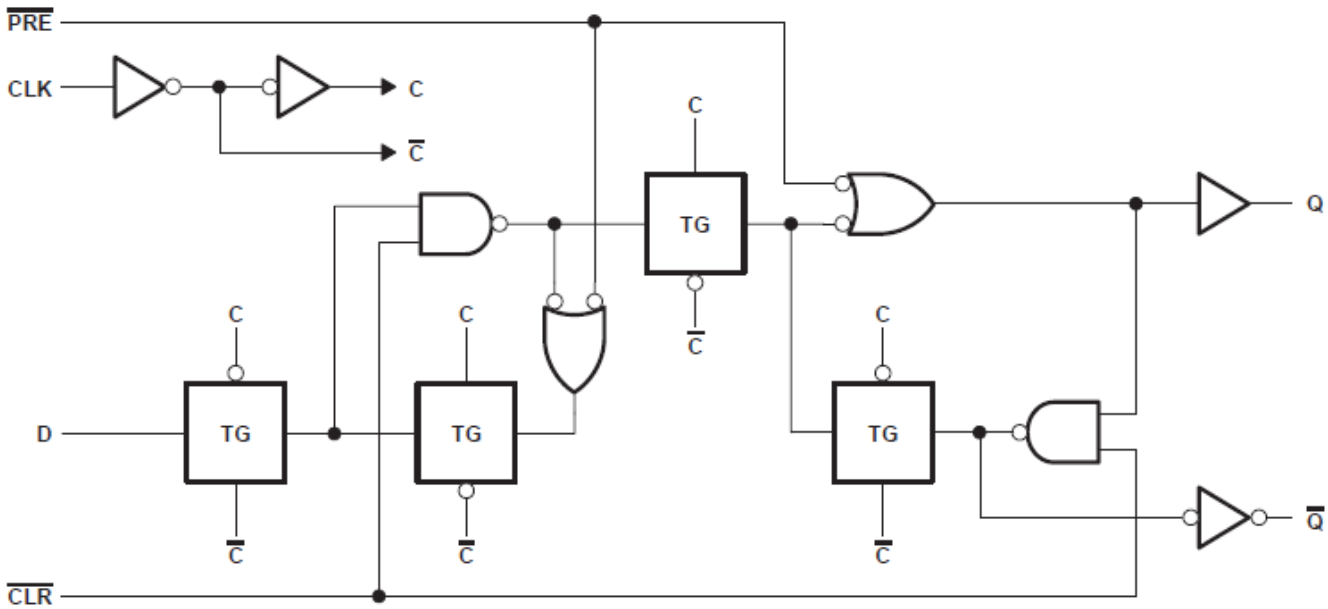


Figure 6-1. Logic Diagram (Positive Logic)

6.3 Device Functional Modes

Table 6-1. Function Table (each flip-flop)

INPUTS				OUTPUTS	
$\overline{PRE}$	$\overline{CLR}$	CLK	D	Q	$\overline{Q}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H[1]	H[1]
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q_0	$\overline{Q}_0$

1. This configuration is nonstable; that is, it does not persist when either PRE or CLR returns to its inactive (high) level.

7 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

7.1 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. A 0.1µF capacitor is recommended for this device. Parallel multiple bypass capacitors to reject different frequencies of noise is acceptable. 0.1µF and 1µF capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results, as shown in Figure 7-1.

7.2 Layout

7.2.1 Layout Guidelines

When using multiple bit logic devices inputs should not ever float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only three of the four buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified below are the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} whichever make more sense or is more convenient. Floating outputs is generally acceptable, unless the part is a transceiver. If the transceiver has an output enable pin it will disable the outputs section of the part when asserted. This will not disable the input section of the I.O's so they also cannot float when disabled.

7.2.2 Layout Example

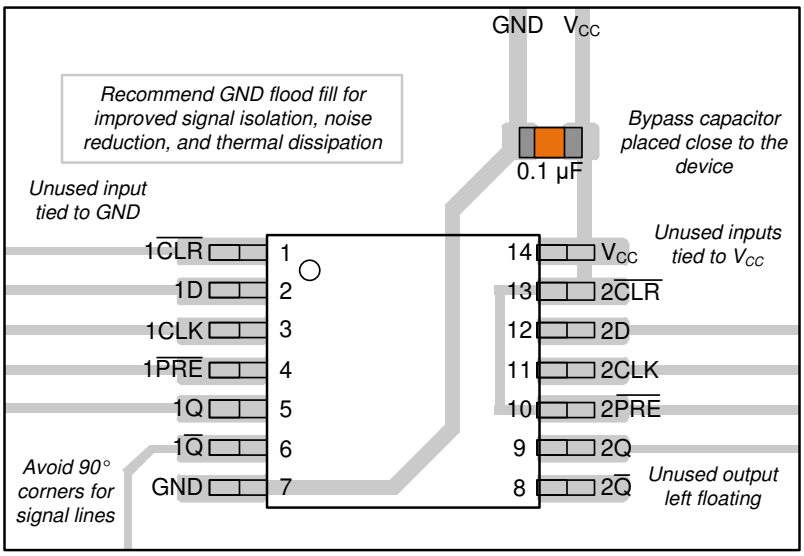


Figure 7-1. Example Layout for the in the SNx4ACT74 Package

8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

8.1 Documentation Support (Analog)

8.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 8-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN54ACT74	Click here	Click here	Click here	Click here	Click here
SN74ACT74	Click here	Click here	Click here	Click here	Click here

8.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

8.3 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

8.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.
All trademarks are the property of their respective owners.

8.5 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.6 Glossary

TI Glossary — This glossary lists and explains terms, acronyms, and definitions.

9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision I (July 2024) to Revision J (April 2025)	Page
• Added BQA Package	3
• Added BQA thermal information	4

Changes from Revision H (October 2003) to Revision I (July 2024) **Page**

- Added *Device Information* table, *Pin Functions* table, *Thermal Information* table, *Device Functional Modes, Application and Implementation* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section 1
- Updated the numbering format for tables, figures, and cross-references throughout the document..... 1
- Updated RθJA values: D = 86 to 119.9, PW = 113 to 145.7, all values in °C/W..... 4

10 Mechanical, Packaging, and Orderable Information

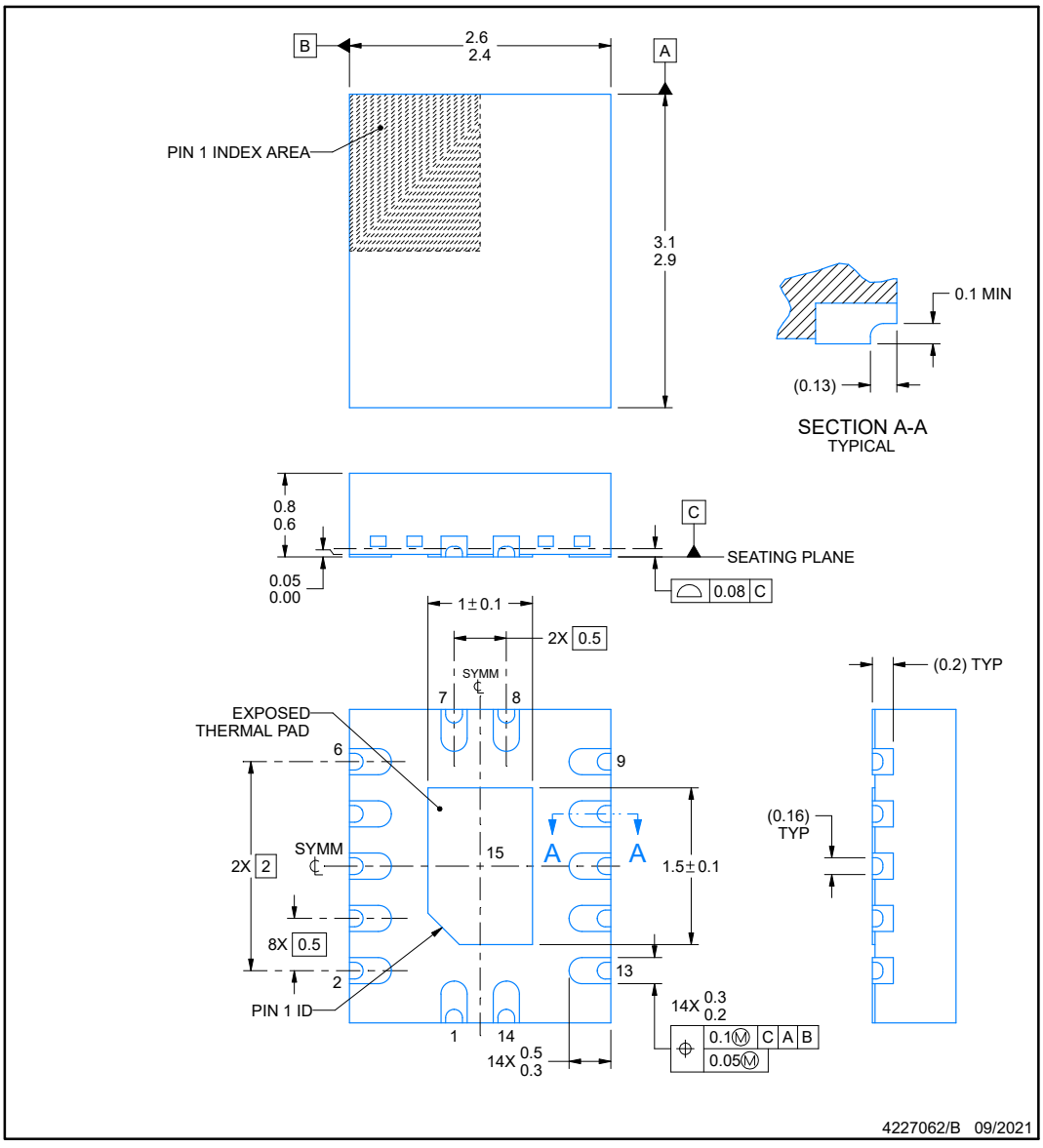
The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGE OUTLINE

BQA0014B

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



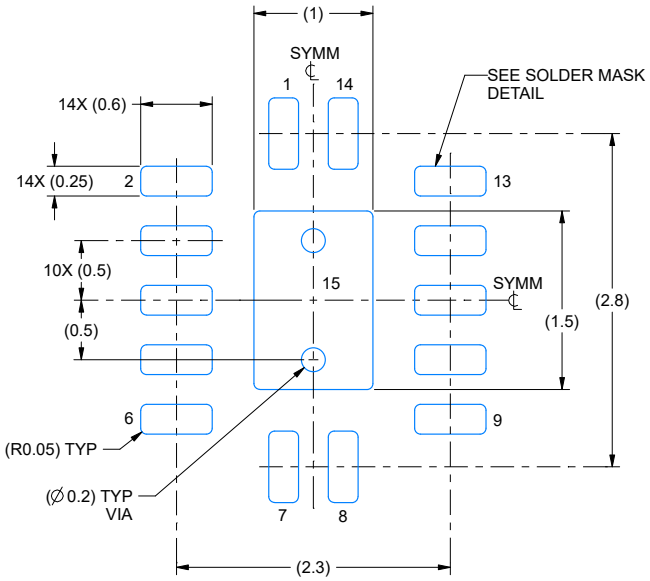
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

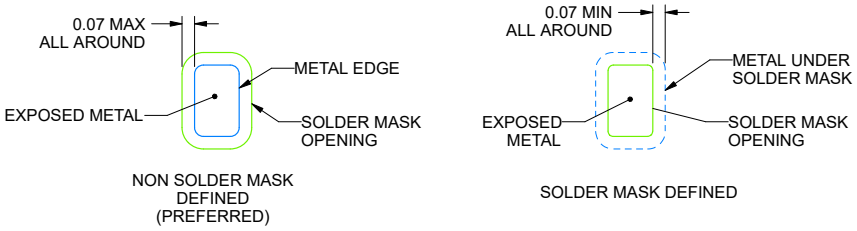
EXAMPLE BOARD LAYOUT

BQA0014B — **WQFN - 0.8 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X



SOLDER MASK DETAILS

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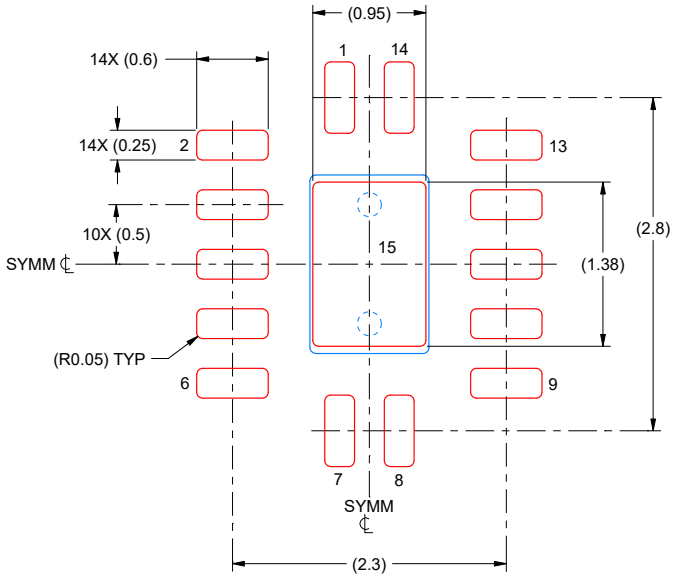
NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

BQA0014B — **WQFN - 0.8 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 20X

EXPOSED PAD 15
87% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8752501M2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8752501M2A SNJ54ACT 74FK	Samples
5962-8752501MCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8752501MCA SNJ54ACT74J	Samples
5962-8752501MDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8752501MDA SNJ54ACT74W	Samples
SN74ACT74D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-40 to 85	ACT74	
SN74ACT74DBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD74	Samples
SN74ACT74DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT74	Samples
SN74ACT74N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74ACT74N	Samples
SN74ACT74NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74ACT74N	Samples
SN74ACT74NSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT74	Samples
SN74ACT74PW	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 85	AD74	
SN74ACT74PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 85	AD74	Samples
SN74ACT74PWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD74	Samples
SNJ54ACT74FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8752501M2A SNJ54ACT 74FK	Samples
SNJ54ACT74J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8752501MCA SNJ54ACT74J	Samples
SNJ54ACT74W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8752501MDA SNJ54ACT74W	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

OTHER QUALIFIED VERSIONS OF SN54ACT74, SN74ACT74 :

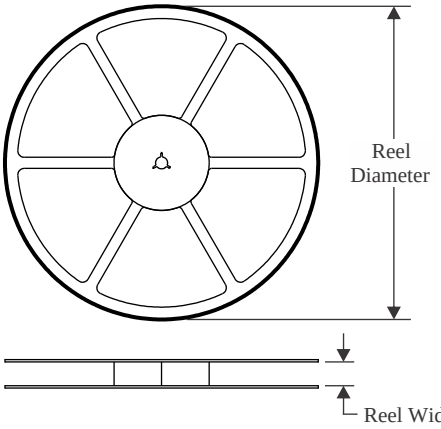
- Catalog : SN74ACT74
- Enhanced Product : SN74ACT74-EP, SN74ACT74-EP
- Military : SN54ACT74

NOTE: Qualified Version Definitions:

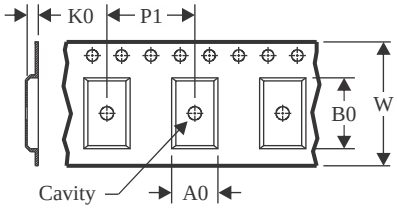
- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

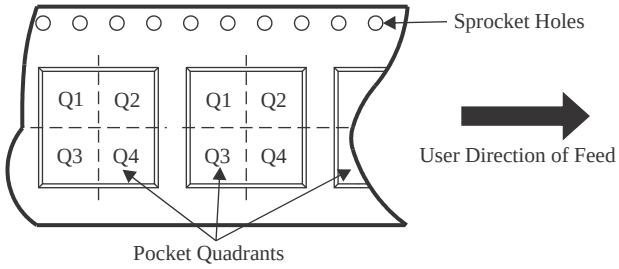


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

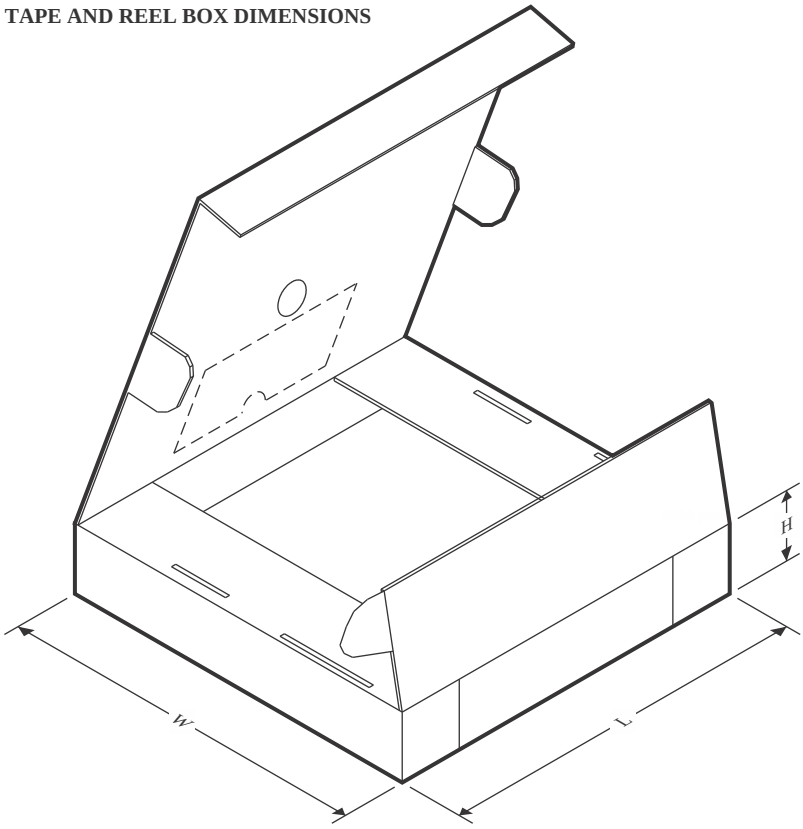
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ACT74DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74ACT74DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ACT74DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ACT74NSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74ACT74PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74ACT74PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74ACT74PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74ACT74PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

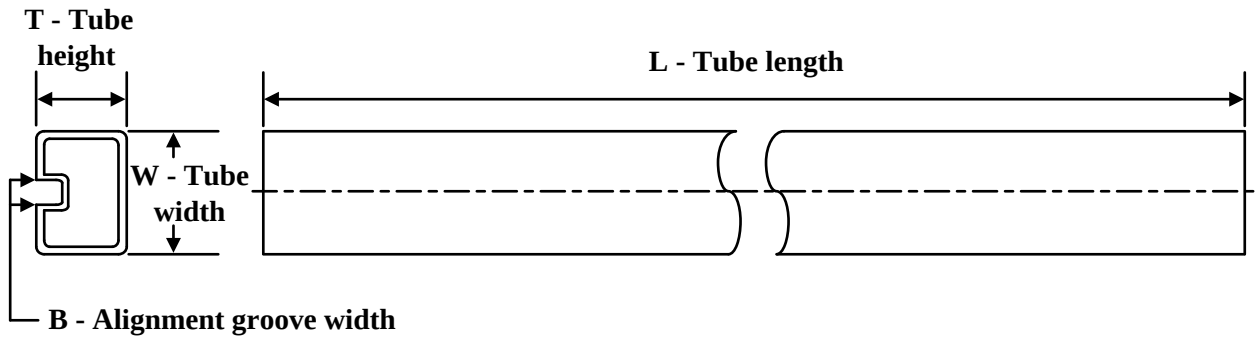
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

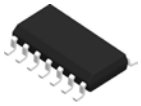
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ACT74DBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74ACT74DR	SOIC	D	14	2500	353.0	353.0	32.0
SN74ACT74DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74ACT74NSR	SOP	NS	14	2000	356.0	356.0	35.0
SN74ACT74PWR	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74ACT74PWR	TSSOP	PW	14	2000	353.0	353.0	32.0
SN74ACT74PWRG4	TSSOP	PW	14	2000	353.0	353.0	32.0
SN74ACT74PWRG4	TSSOP	PW	14	2000	356.0	356.0	35.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-8752501M2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-8752501MDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74ACT74N	N	PDIP	14	25	506	13.97	11230	4.32
SN74ACT74N	N	PDIP	14	25	506	13.97	11230	4.32
SN74ACT74NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74ACT74NE4	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54ACT74FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54ACT74W	W	CFP	14	25	506.98	26.16	6220	NA

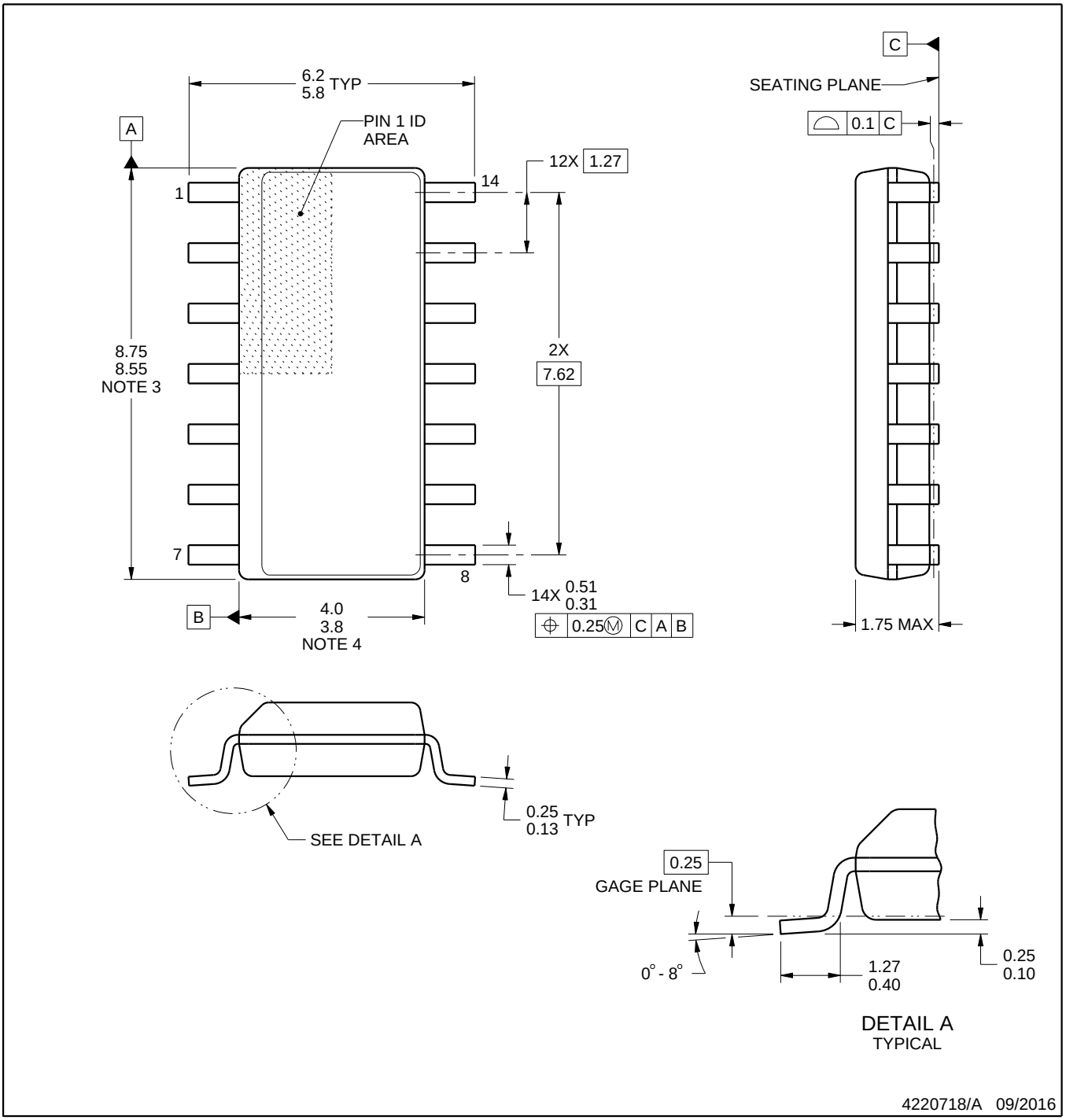


PACKAGE OUTLINE

D0014A

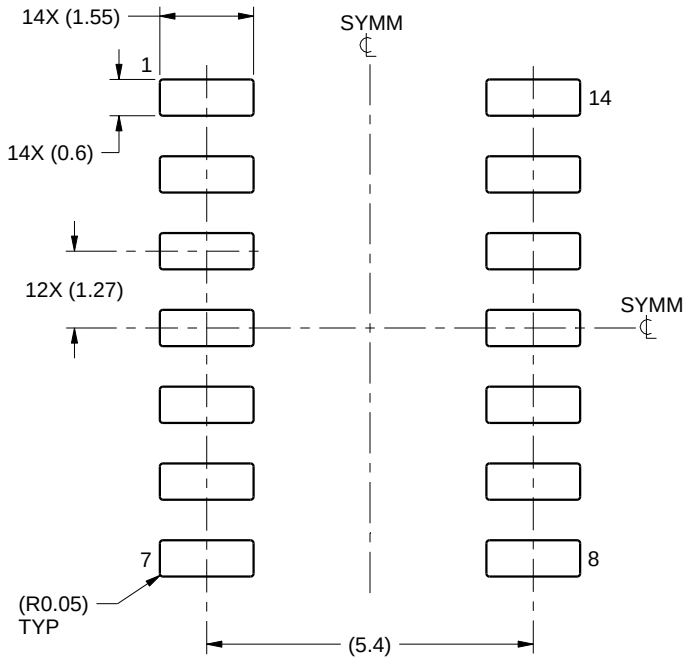
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

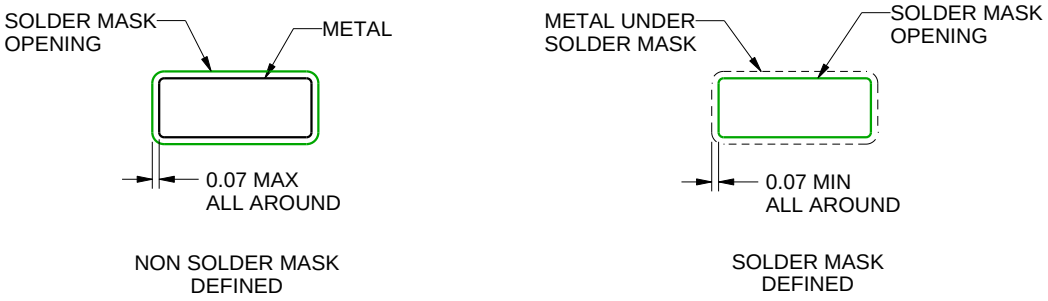


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

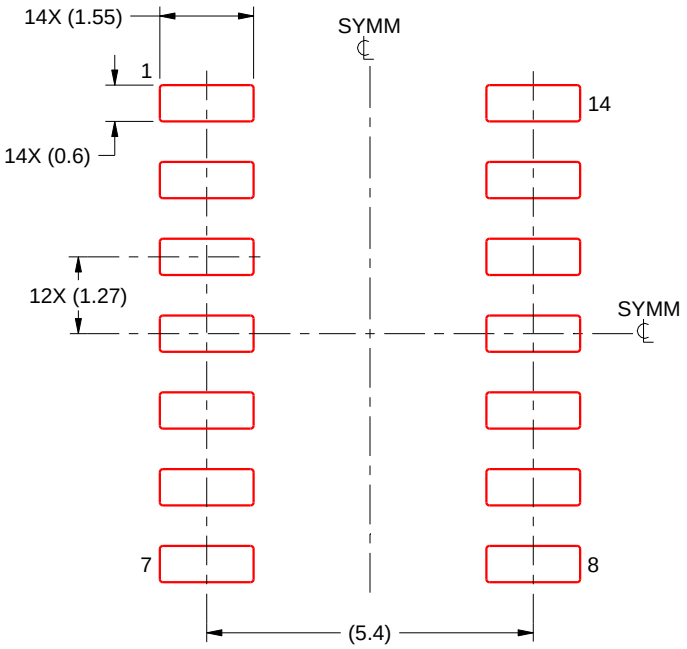
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

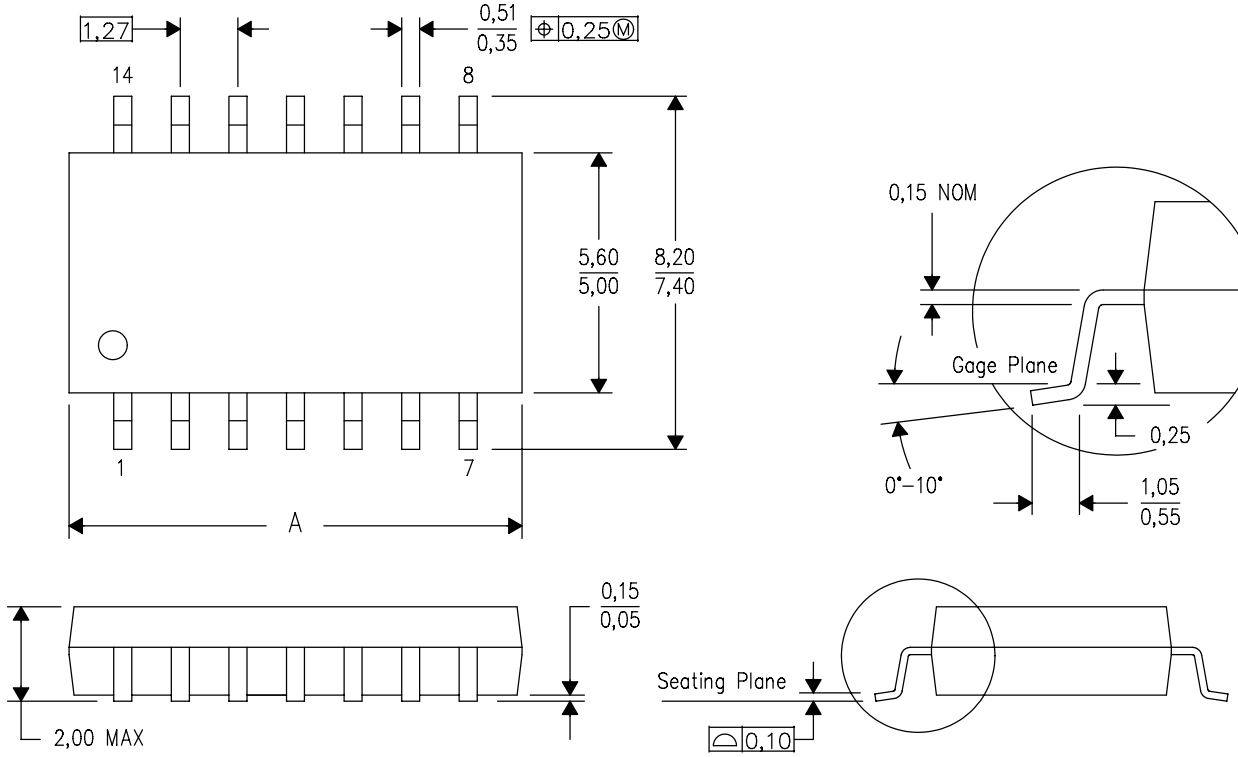
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN

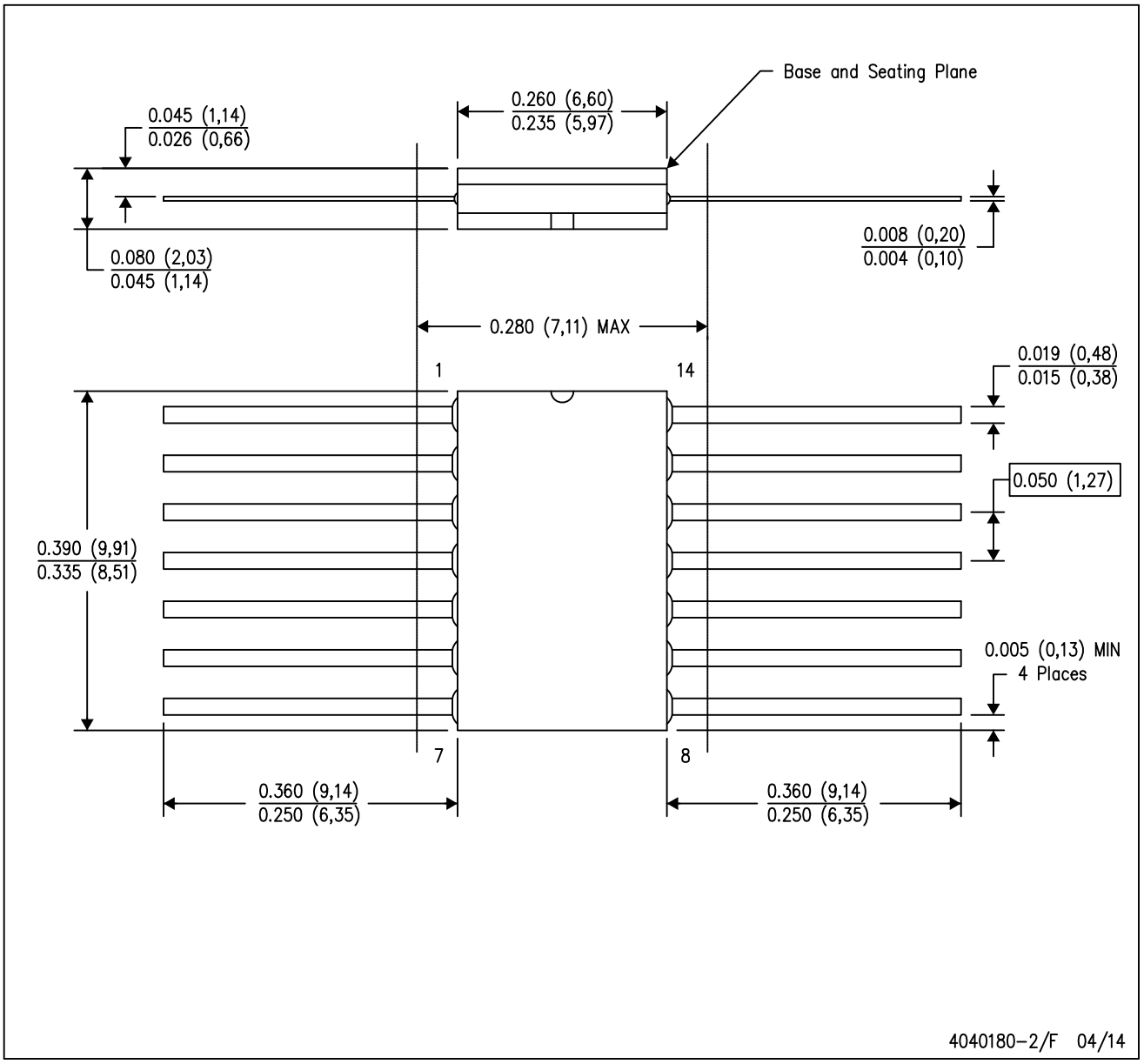


DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R–GDFP–F14) CERAMIC DUAL FLATPACK



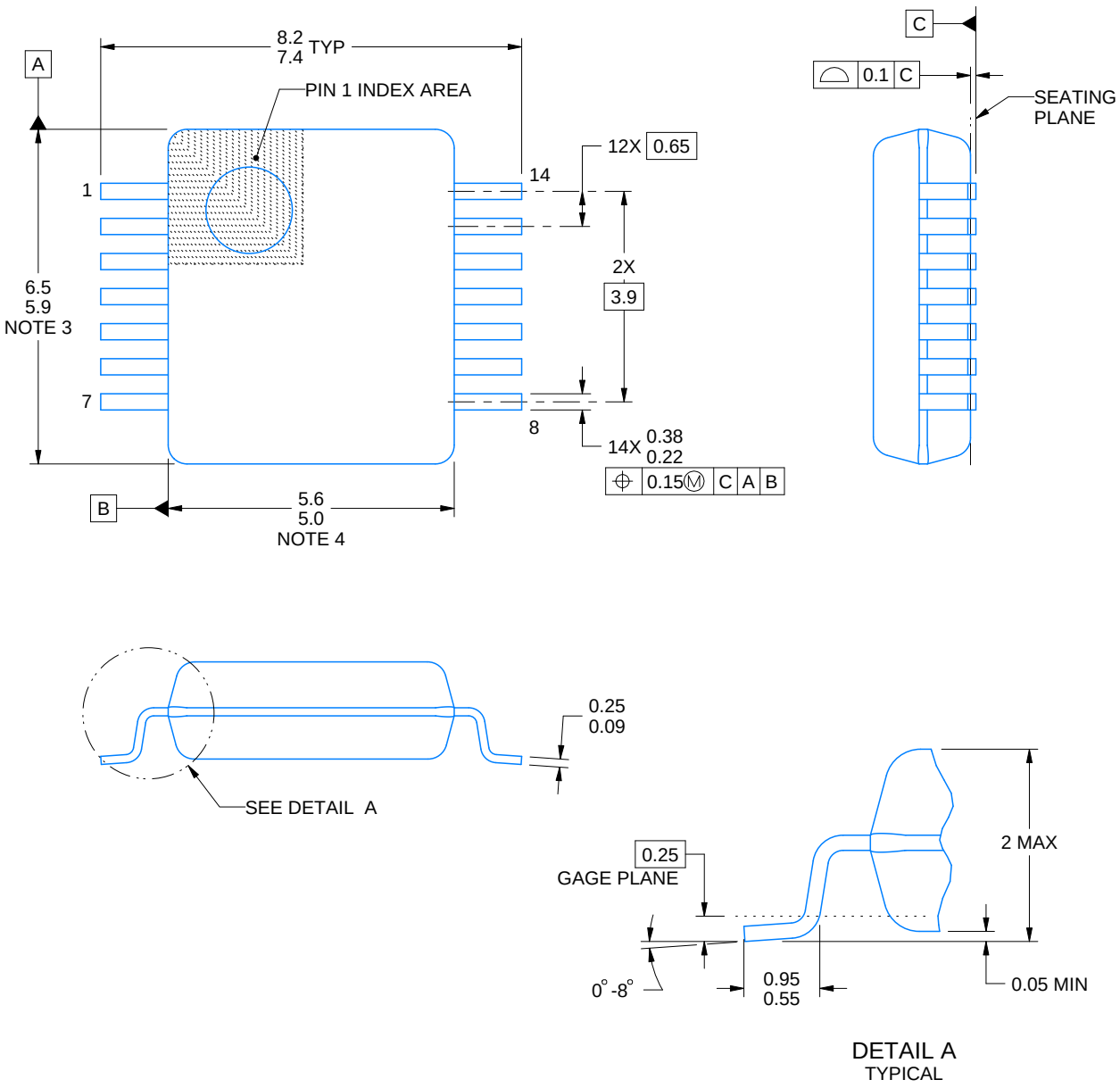
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14

PACKAGE OUTLINE

DB0014A

SSOP - 2 mm max height

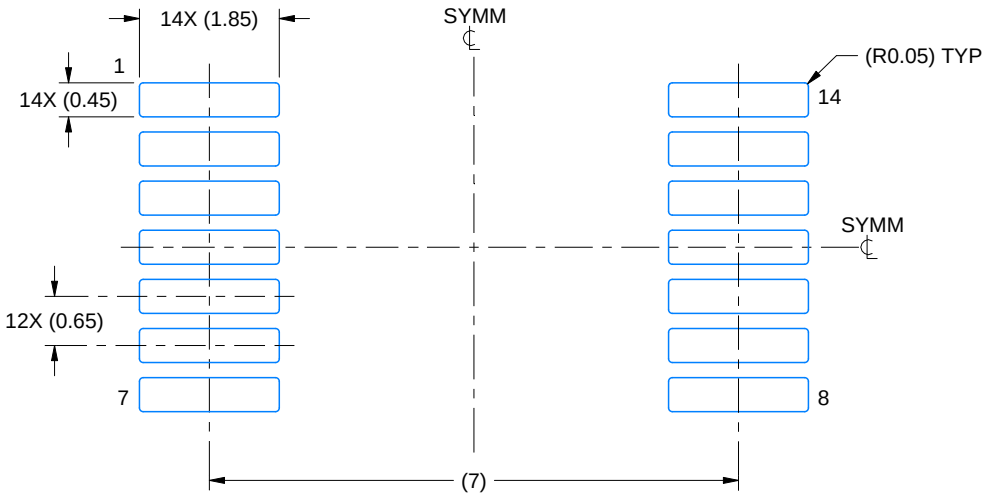
SMALL OUTLINE PACKAGE



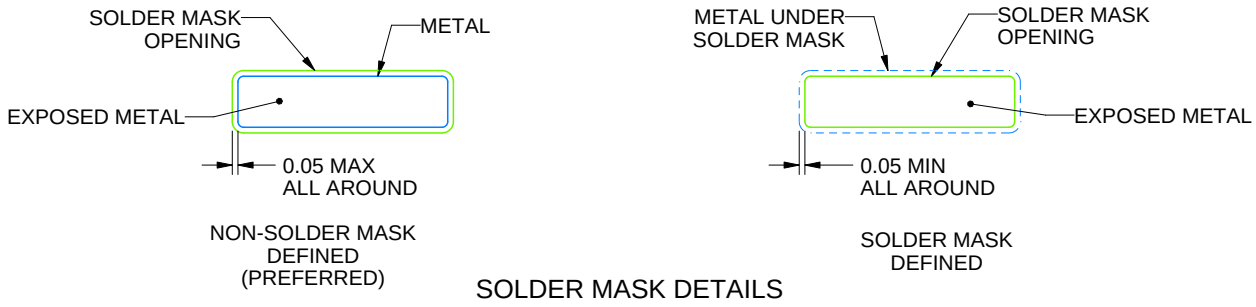
4220762/A 05/2024

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

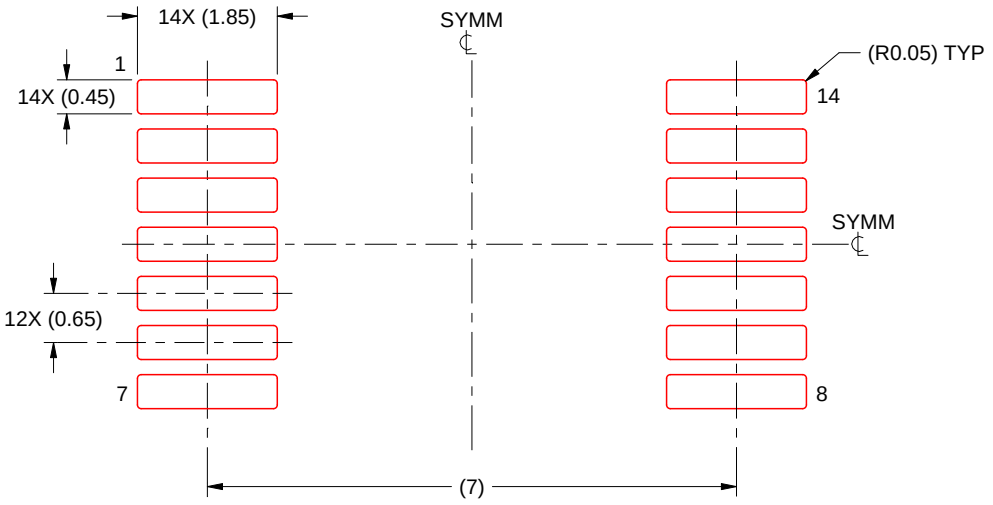


SOLDER MASK DETAILS

4220762/A 05/2024

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220762/A 05/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

GENERIC PACKAGE VIEW

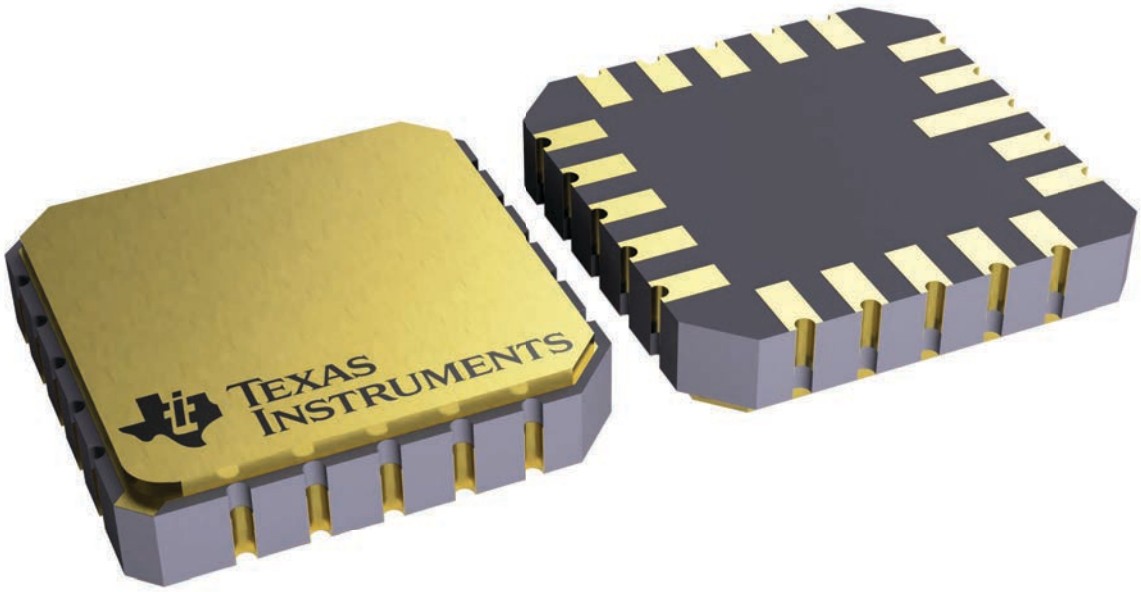
FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

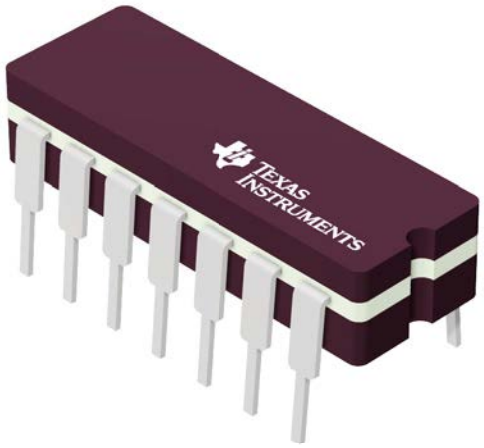


4229370VA\

GENERIC PACKAGE VIEW

J 14 CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

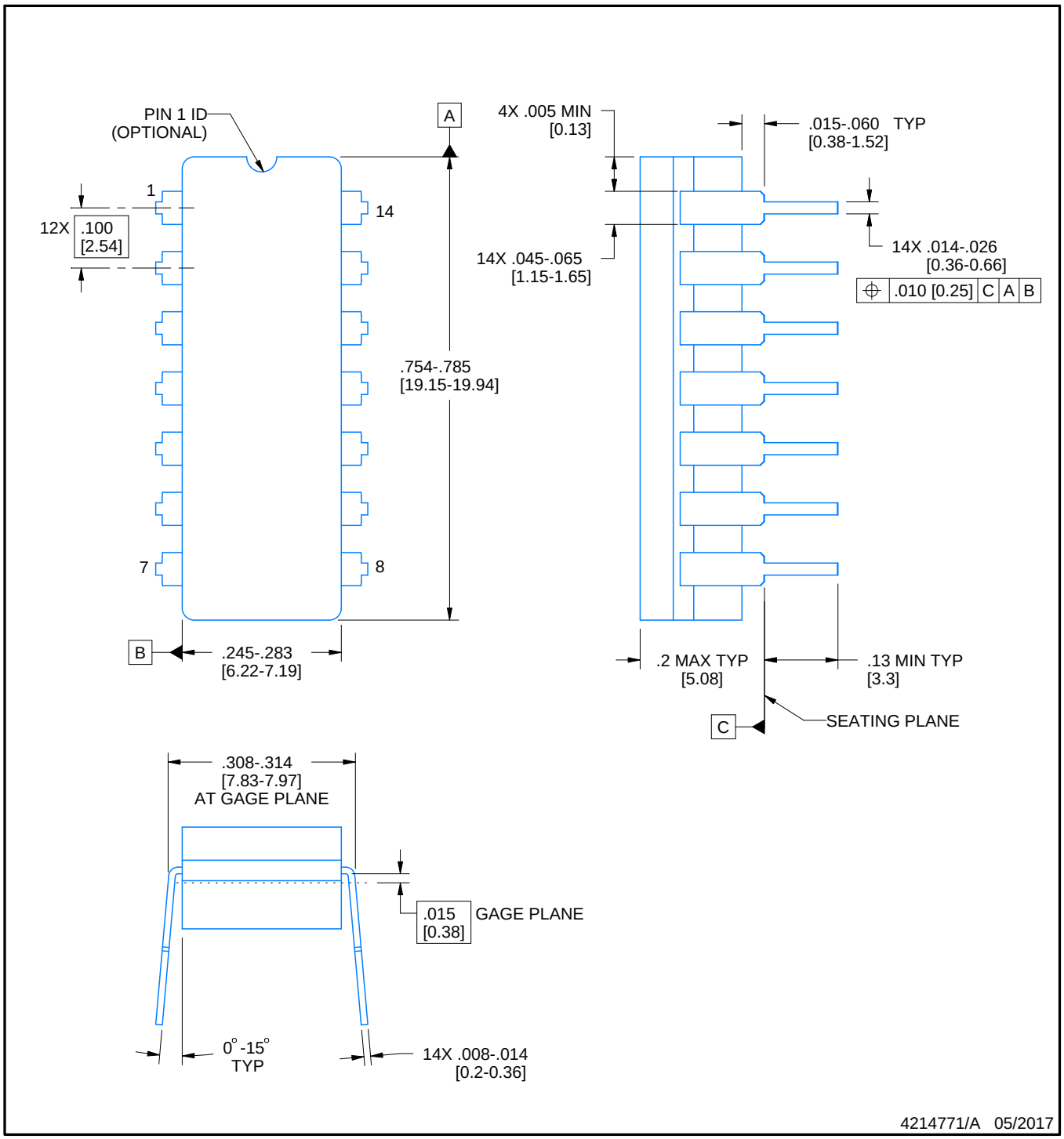
4040083-5/G

PACKAGE OUTLINE

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

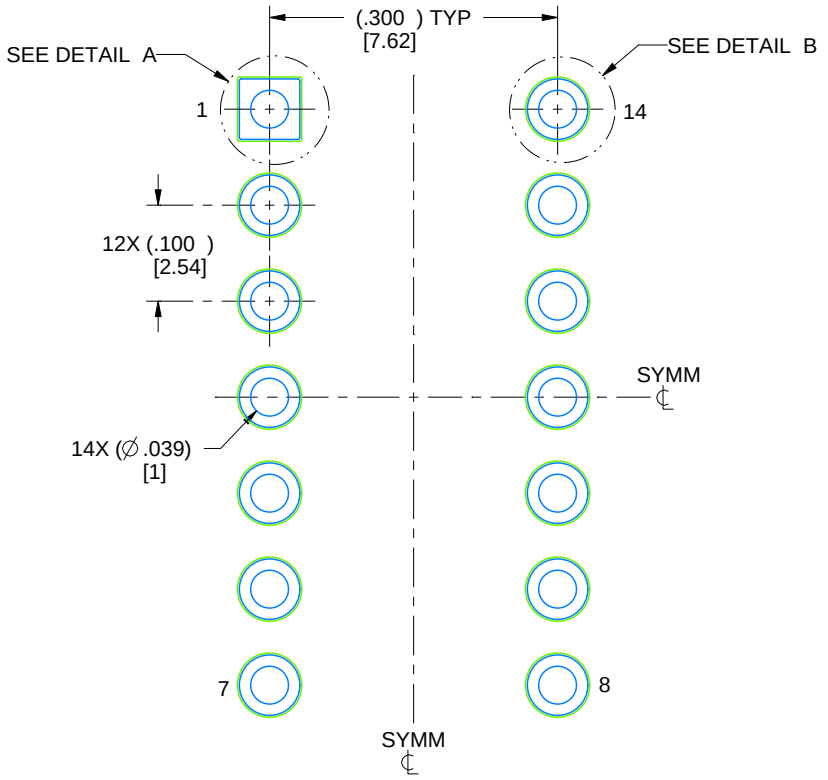
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermitically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

EXAMPLE BOARD LAYOUT

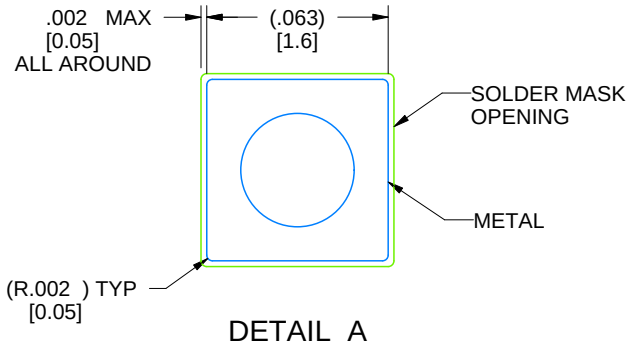
J0014A

CDIP - 5.08 mm max height

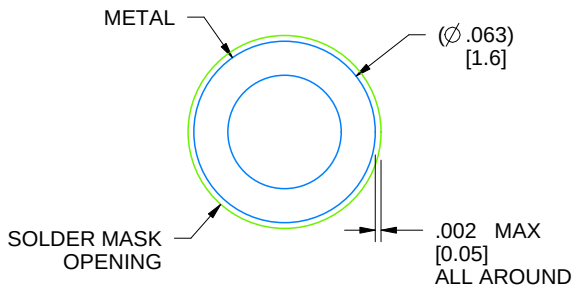
CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X



DETAIL A
SCALE: 15X



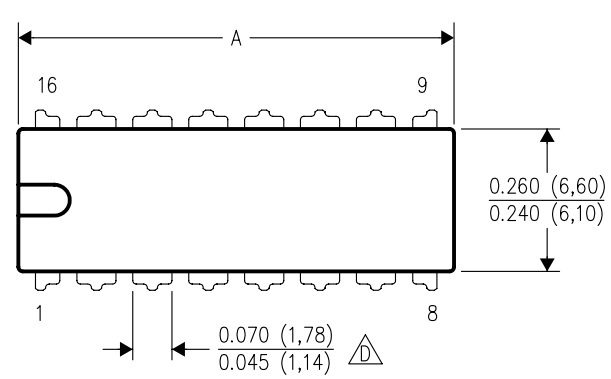
DETAIL B
13X, SCALE: 15X

4214771/A 05/2017

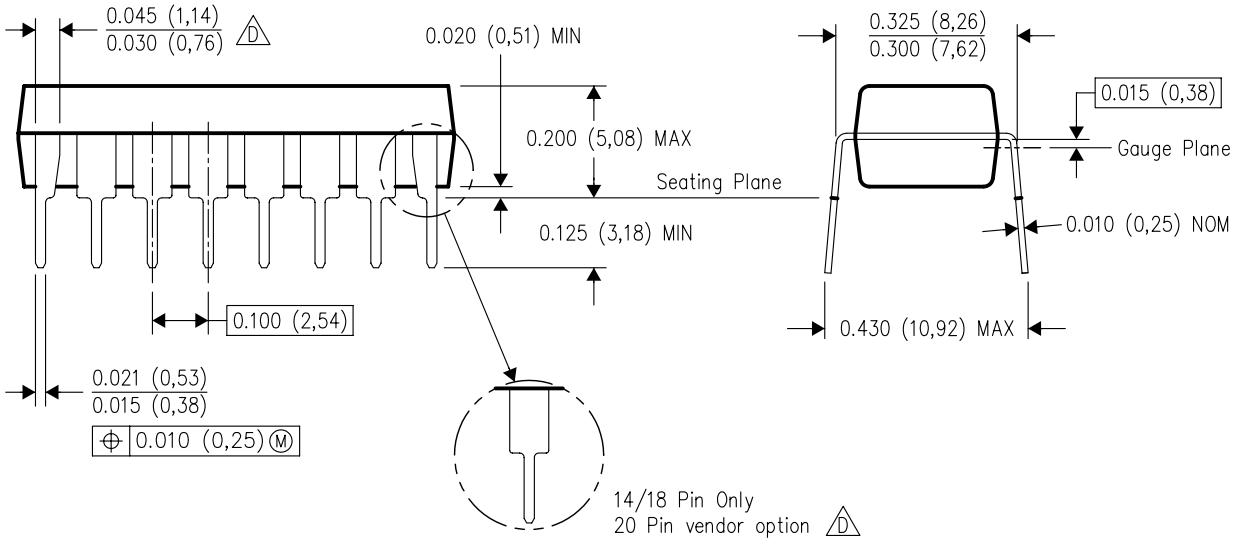
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

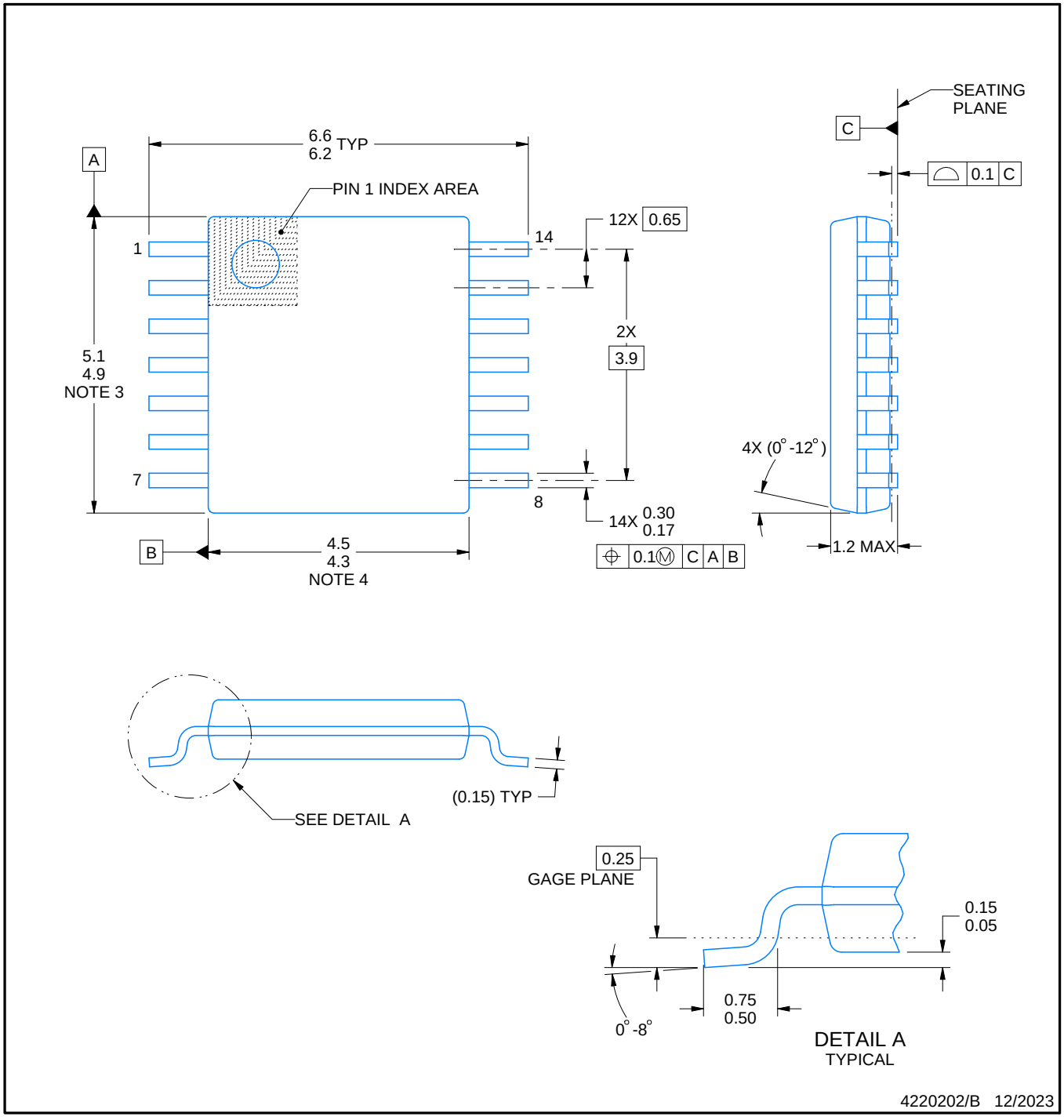
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

PACKAGE OUTLINE

PW0014A

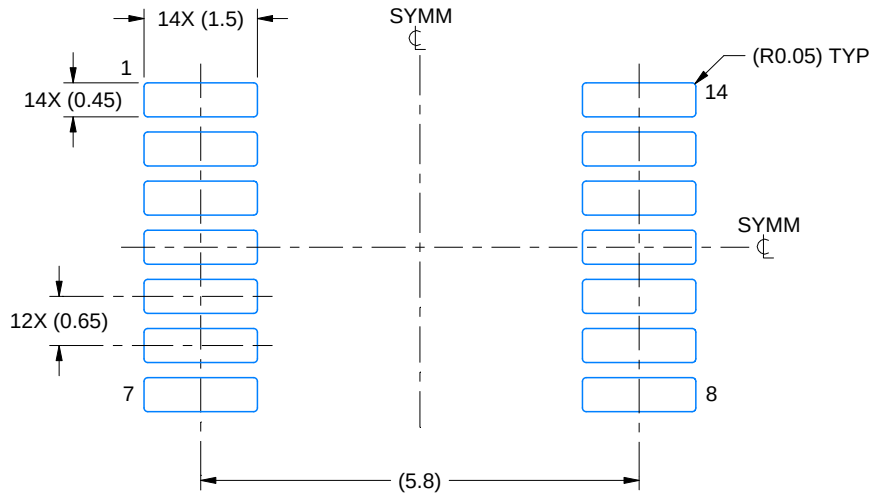
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

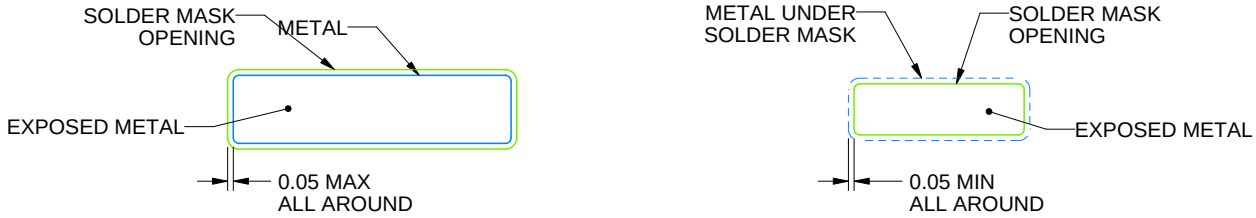


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

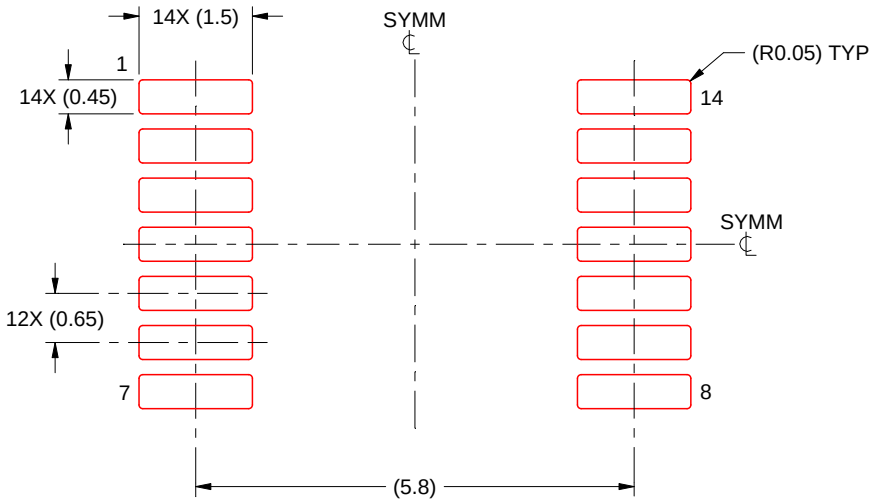


SOLDER MASK DETAILS

4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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